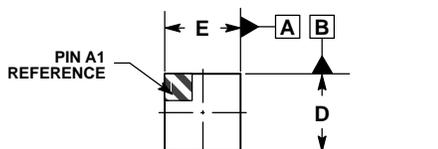




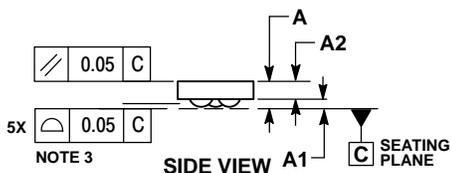
SCALE 4:1

WLCSP5, 0.86x0.84
 CASE 567DD
 ISSUE D

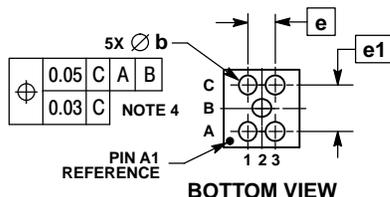
DATE 14 JUL 2016



TOP VIEW

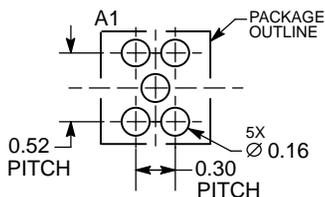


SIDE VIEW



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	---	---	0.39
A1	0.10	0.12	0.14
A2	0.23 REF		
b	0.14	0.16	0.18
D	0.84	0.86	0.88
E	0.82	0.84	0.86
e	0.30 BSC		
e1	0.52 BSC		

GENERIC MARKING DIAGRAM*



- X = Specific Device Code
- Y = Year
- M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WLCSP5, 0.86X0.84	PAGE 1 OF 2

